

S86 8/5/02

L Number	Hits	Search Text	DB	Time stamp
2	1979	438/108.cccls. or 438/118.cccls. or 438/119.cccls. or 438/124.cccls. or 438/126.cccls. or 438/127.cccls.	USPAT	2002/08/05 12:50
1	722	438/106.cccls.	USPAT	2002/08/05 12:51
4	291	438/106.cccls. and (438/108.cccls. or 438/118.cccls. or 438/119.cccls. or 438/124.cccls. or 438/126.cccls. or 438/127.cccls.)	USPAT	2002/08/05 13:58
5	2410	438/106.cccls. or (438/108.cccls. or 438/118.cccls. or 438/119.cccls. or 438/124.cccls. or 438/126.cccls. or 438/127.cccls.)	USPAT	2002/08/05 13:58
6	470	(438/106.cccls. or (438/108.cccls. or 438/118.cccls. or 438/119.cccls. or 438/124.cccls. or 438/126.cccls. or 438/127.cccls.)) and ((encapsul\$5 or resin or paste or goop or adhesive or polymer) with (pool or reservoir or cup or well))	USPAT	2002/08/05 14:00
7	152	((438/106.cccls. or (438/108.cccls. or 438/118.cccls. or 438/119.cccls. or 438/124.cccls. or 438/126.cccls. or 438/127.cccls.)) and ((encapsul\$5 or resin or paste or goop or adhesive or polymer) with (pool or reservoir or cup or well))) and (flip adj chip)	USPAT	2002/08/05 14:00
8	97382	((encapsul\$5 or resin or paste or goop or adhesive or polymer) with (pool or reservoir or cup or well))	USPAT	2002/08/05 14:01
9	763	((encapsul\$5 or resin or paste or goop or adhesive or polymer) with (pool or reservoir or cup or well))) and ((flip-chip) or (flip adj chip))	USPAT	2002/08/05 14:01
10	124931	((encapsul\$5 or resin or paste or goop or adhesive or polymer) with (pool or reservoir or cup or well))	USPAT; EPO; JPO; DERWENT; IBM_TDB	2002/08/05 14:01
12	785	((encapsul\$5 or resin or paste or goop or adhesive or polymer) with (pool or reservoir or cup or well))) and ((flip adj chip) or (flip-chip))	USPAT; EPO; JPO; DERWENT; IBM_TDB	2002/08/05 14:03
13	137	((encapsul\$5 or resin or paste or goop or adhesive or polymer) with (pool or reservoir or cup or well))) and (resin adj pool)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2002/08/05 14:33
3	1688	(438/108.cccls. or 438/118.cccls. or 438/119.cccls. or 438/124.cccls. or 438/126.cccls. or 438/127.cccls.) not 438/106.cccls.	USPAT	2002/08/05 15:25
15	459	((438/108.cccls. or 438/118.cccls. or 438/119.cccls. or 438/124.cccls. or 438/126.cccls. or 438/127.cccls.) not 438/106.cccls.) and (flip adj chip)	USPAT	2002/08/05 15:38
16	0	(flip adj chip) near (dip or dipped or dipping or dips)	USPAT	2002/08/05 15:39
17	0	(flip adj chip) near (dip\$5)	USPAT	2002/08/05 15:39
18	34	(flip adj chip) with (dip or dipped or dipping or dips)	USPAT	2002/08/05 15:39
-	9	flip adj chip adj bonding adj apparatus	USPAT	2002/08/04 17:49
-	224	berezny.xa.	USPAT	2002/08/04 17:49
-	126	berezny.xa. and nema	USPAT	2002/08/04 17:50
-	25	(berezny.xa. and nema) and flip	USPAT	2002/08/04 17:51
-	3963	murakami.in.	USPAT	2002/08/04 17:51
-	63	murakami.in. and NEC	USPAT	2002/08/04 18:02
-	243	((flip adj chip) or (flip-chip)) and (pool or pools reservoir or reservoir or (resin adj pool))	USPAT	2002/08/04 18:07
-	0	((flip adj chip) or (flip-chip)) near (reservoir or reservoir or (resin adj pool))	USPAT	2002/08/04 18:08

-	180	((flip adj chip) or (flip-chip)) and (reservoir or reservoir or (resin adj pool))	USPAT	2002/08/05 12:49
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